PCN-CSG-001597

Product Change Notice

Issue Date: September 23, 2019

Change Type:

Add ASE Taiwan as Bump supplier

Parts Affected:

BCM88470CB0IFSBG
BCM88470CB0KFSBG
BCM88471CB0IFSBG
BCM88471CB0KFSBG
BCM88476CB0KFSBG

Description and Extent of Change:

Additional CuP Bump supplier - ASE TAIWAN

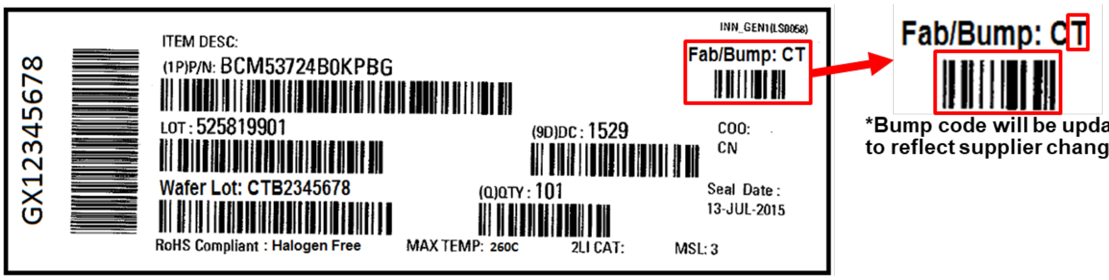
Reasons for Change:

- Adding bump supplier. Broadcom reserves the right to manage supplier.
- The construction of the bump is identical
- SPIL Taiwan has internally qualified the direct CuP bumping and in volume production.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification will be performed on representative products to insure normal parametric distribution, consistent electrical performance, and reliability.

Box label will be changed to identify correct bump supplier:



GX12345678
ITEM DESC:
(1P)P/N: BCM53724B0KPBG
LOT: 525819901
Wafer Lot: CTB2345678
(9D)DC: 1529
(Q)QTY: 101
INN_GEN1(LS0058)
Fab/Bump: CT
COO: CN
Seal Date: 13-JUL-2015
RoHS Compliant : Halogen Free
MAX TEMP: 260C
2LI CAT:
MSL: 3

*Bump code will be updated to reflect supplier change

Effective Date of Change:

Product shipments using this change will be effective 90 days from the issue date.

Qualification Data:

Bump Type	OSAT	Bump Supplier	Package Type	MSL3	HTSL 150C 1000 Hours	TCT Cond B 1000 Cycles	UHAST 96 Hours
CuP	ASE TAIWAN	ASE TAIWAN	FCBGA+HS	PASS	0/77	0/77	0/77

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.